

# Cascadable Silicon Bipolar MMIC Amplifier

Technical Data

#### **MSA-9970**

#### **Features**

- Open Loop Feedback Amplifier
- Performance Flexibility with User Selected External Feedback for:

Broadband Minimum Ripple Amplifiers Low Return Loss Amplifiers Negative Gain Slope Amplifiers

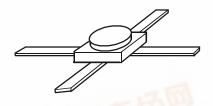
- Usable Gain to 6.0 GHz
- 16.0 dB Typical Open Loop Gain at 1.0 GHz
- 14.5 dBm Typical P<sub>1 dB</sub> at 1.0 GHz
- Hermetic Gold-ceramic Microstrip Package

### **Description**

The MSA-9970 is a high performance silicon bipolar Monolithic Microwave Integrated Circuit (MMIC) housed in a hermetic high reliability package. This MMIC is designed with high open loop gain and is intended to be used with external resistive and reactive feedback elements to create a variety of special purpose gain blocks.

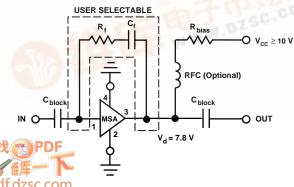
Applications include very broadband, minimum ripple amplifiers with extended low frequency performance possible through the use of a high valued external feedback blocking capacitor; extremely well matched (–20 dB return loss) amplifiers; and negative gain slope amplifiers for flattening MMIC cascades.

### 70 mil Package



The MSA-series is fabricated using HP's  $10\,\mathrm{GHz}\,\mathrm{f}_\mathrm{T}, 25\,\mathrm{GHz}\,\mathrm{f}_\mathrm{MAX},$  silicon bipolar MMIC process which uses nitride self-alignment, ion implantation, and gold metallization to achieve excellent performance, uniformity and reliability. The use of an external bias resistor for temperature and current stability also allows bias flexibility.

## **Typical Biasing Configuration**



## MSA-9970 Absolute Maximum Ratings

Parameter	Absolute Maximum <sup>[1]</sup>
Device Current	80 mA
Power Dissipation <sup>[2,3]</sup>	750 mW
RF Input Power	+13dBm
Junction Temperature	200℃
Storage Temperature	–65°C to 200°C

Thermal Resistance $^{[2,4]}$ :						
$\theta_{\rm jc} = 150^{\circ} \text{C/W}$						

#### **Notes:**

- 1. Permanent damage may occur if any of these limits are exceeded.
- 2.  $T_{CASE} = 25$ °C.
- 3. Derate at 6.7 mW/°C for  $T_C > 88$ °C.
- 4. The small spot size of this technique results in a higher, though more accurate determination of  $\theta_{jc}$  than do alternate methods. See MEASUREMENTS section "Thermal Resistance" for more information.

## Electrical Specifications $^{[1]}$ , $T_A = 25$ $^{\circ}$ C

Symbol	Parameters and Test Conditions: $\mathbf{I}_{d}$	Units	Min.	Тур.	Max.	
$G_P$	Power $Gain^{[2]}( S_{21} ^2)$	f = 0.1  GHz f = 1.0  GHz f = 4.0  GHz	dB	14.5 8.0	17.5 16.0 9.0	17.5 10.0
P <sub>1 dB</sub>	Output Power at 1 dB Gain Compression <sup>[2]</sup>	f = 1.0  GHz	dBm		14.5	
IP <sub>3</sub>	Third Order Intercept Point <sup>[2]</sup>	f = 1.0  GHz	dBm		25.0	
Vd	Device Voltage		V	7.0	7.8	8.6
dV/dT	Device Voltage Temperature Coefficient		mV/°C		-16.0	

#### **Notes**:

- 1. The recommended operating current range for this device is 25 to 45 mA. Typical performance as a function of current is on the following page.
- $2.\,$  Open loop value. Adding external feedback will alter device performance.

MSA-9970 Typical Scattering Parameters (Z  $_{0}$  = 50  $\Omega,$   $T_{_{A}}$  = 25  $^{\circ}C,$   $I_{_{d}}$  = 35 mA)

Freq.	$S_1$	1		$S_{21}$			$S_{12}$		$\mathbf{S}_{22}$		
GHz	Mag	Ang	dB	Mag	Ang	dB	Mag	Ang	Mag	Ang	k
0.02	.89	-1	17.5	7.51	179	-37.2	.014	4	.93	-1	1.01
0.05	.90	<b>-</b> 3	17.5	7.47	177	-35.6	.017	34	.92	<b>-</b> 3	.83
0.1	.90	<b>-</b> 6	17.4	7.45	174	-33.2	.022	43	.93	<b>-</b> 6	.70
0.2	.89	<b>-12</b>	17.4	7.43	168	-29.6	.033	61	.93	-13	.39
0.4	.87	<b>-</b> 24	17.2	7.27	156	-24.4	.061	63	.91	<b>–</b> 27	.24
0.6	.85	-36	17.0	7.06	145	-20.8	.091	58	.90	<del>-4</del> 0	.21
0.8	.82	<b>-4</b> 7	16.6	6.78	134	-18.8	.115	52	.87	<b>-</b> 53	.21
1.0	.79	<b>–</b> 59	16.2	6.49	124	-17.0	.141	44	.84	-66	.24
1.5	.72	-86	15.3	5.79	100	-14.6	.186	29	.74	<b>-</b> 96	.28
2.0	.65	-113	14.2	5.10	77	-13.4	.215	16	.64	-123	.34
2.5	.59	-133	13.0	4.45	61	-12.9	.227	7	.57	-143	.39
3.0	.54	-155	11.6	3.79	42	-12.5	.236	<b>-</b> 3	.51	-163	.46
3.5	.53	-174	10.3	3.28	26	-12.4	.239	-14	.45	178	.53
4.0	.52	168	9.2	2.87	10	-12.5	.238	<b>-</b> 22	.39	164	.59
4.5	.53	152	8.0	2.51	<del>-4</del>	-12.6	.234	-30	.34	155	.66
5.0	.55	140	6.9	2.21	-17	-12.8	.228	<b>–</b> 37	.31	153	.72
5.5	.55	130	5.8	1.94	<b>-</b> 31	-13.2	.220	<del>-4</del> 4	.30	154	.80
6.0	.55	121	4.6	1.70	<b>-4</b> 3	-13.6	.209	<del>-4</del> 8	.32	157	.88
6.5	.56	114	3.5	1.50	<b>-</b> 53	-13.8	.203	<b>-</b> 54	.37	158	.94
7.0	.56	107	2.6	1.34	<b>-</b> 63	-14.0	.201	<b>–</b> 59	.42	157	.97

A model for this device is available in the DEVICE MODELS section.

# Typical Performance, $T_A = 25^{\circ}C$

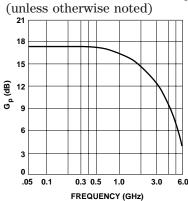


Figure 1. Open Loop Power Gain vs. Frequency,  $I_d=35\ mA$ .

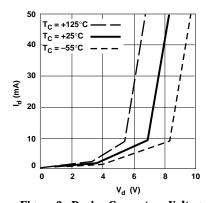


Figure 2. Device Current vs. Voltage.

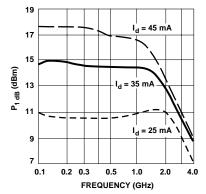


Figure 3. Open Loop Output Power at 1 dB Gain Compression vs. Frequency.

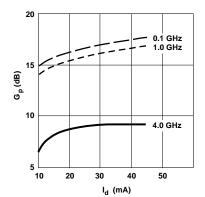


Figure 4. Open Loop Power Gain vs. Current.

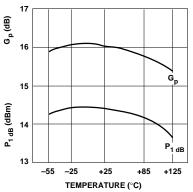


Figure 5. Open Loop Output Power at 1 dB Gain Compression and Open Loop Power Gain vs. Case Temperature, f=1.0~GHz,  $I_d=35~mA$ .

## 70 mil Package Dimensions

